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CSTIC 2026

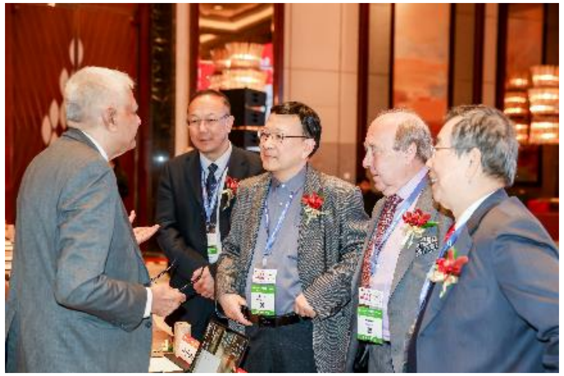
Conference of Science & Technology for Integrated Circuits (CSTIC) 2026

March 22-24， 2026

CSTIC 2026 Grand Opening

CSTIC 2026 Plenary Session

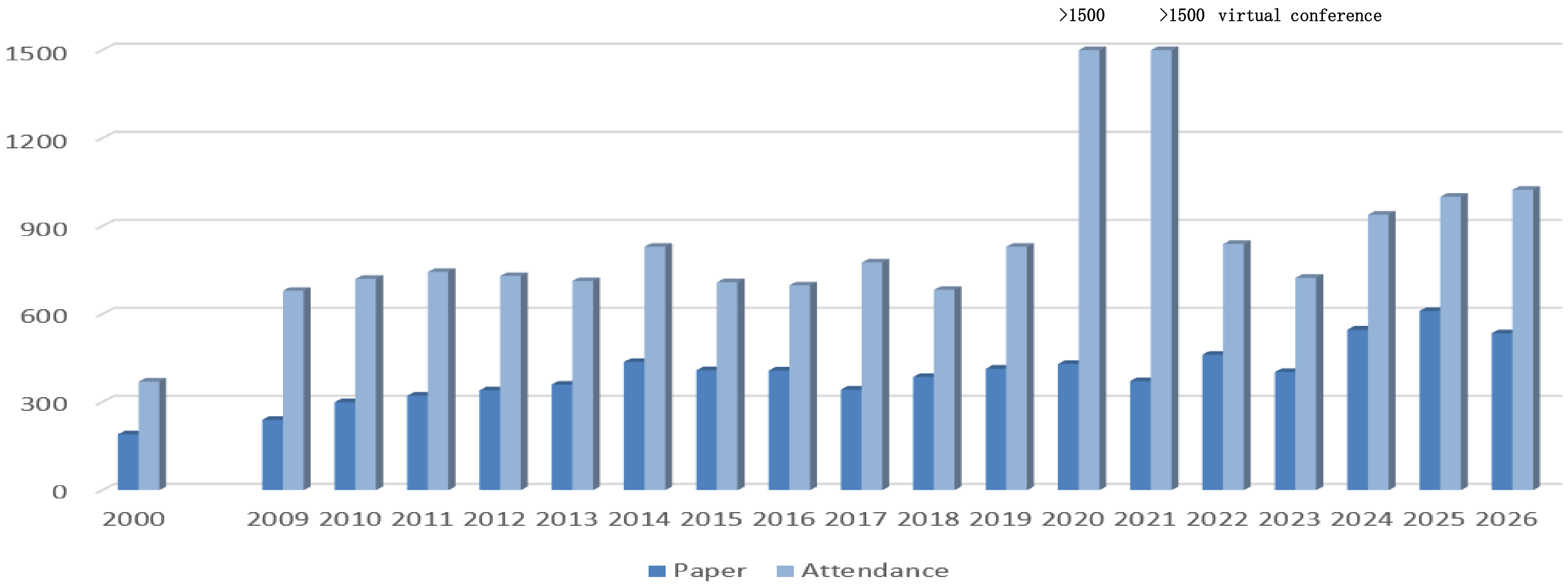
CSTIC 10 Symposiums, Panels, Posters and Tutorials



CSTIC 10 Symposiums, Panels, Posters and Tutorials

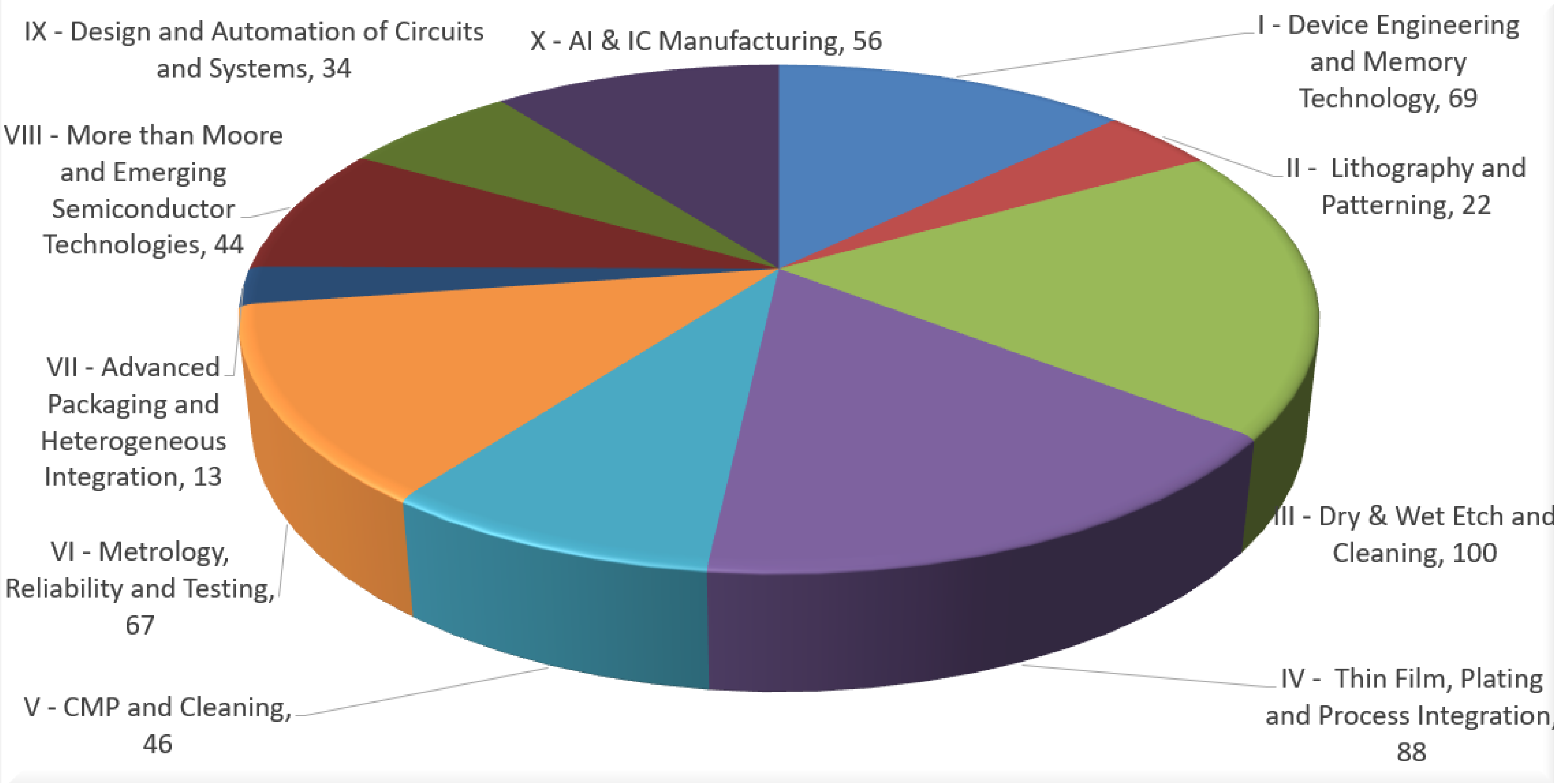
CSTIC 2026 Data

- Largest and most comprehensive, influential annual industrial semiconductor technology conference in China and Asia
- **535 abstracts** have been collected, while **1024 registered attendees** joined the onsite conference. Speakers and attendees came from 20 countries and districts, including Austria, Belgium, Canada, Germany, Israel, Italy, Japan, Korea, Malaysia, Netherlands, Poland, Russia, Singapore, Sweden, Switzerland, UK, US, Hongkong China, Taiwan China and Mainland China。



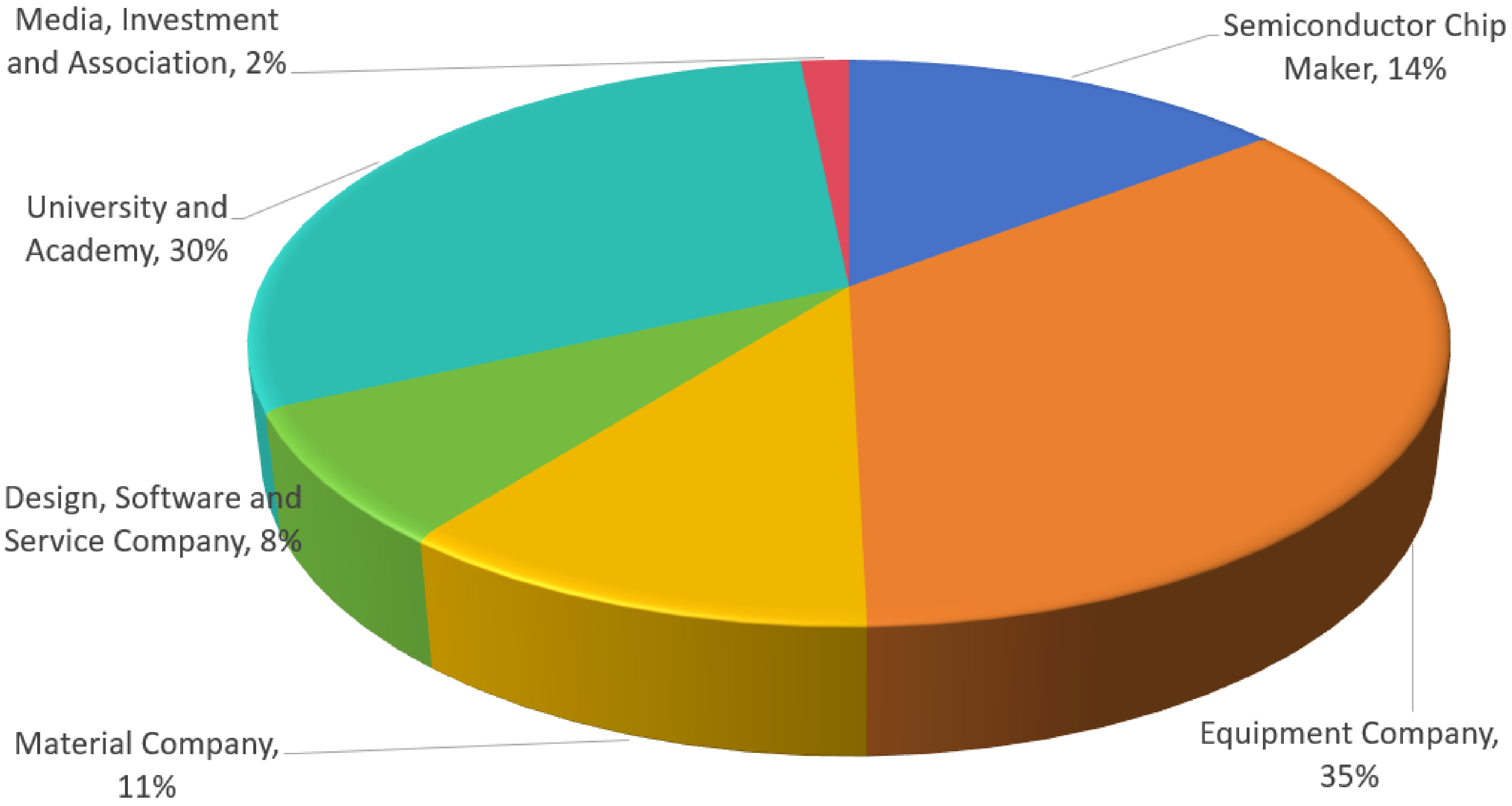
CSTIC 2026 Symposiums

Top 3 abstract submission symposiums are III, IV and I



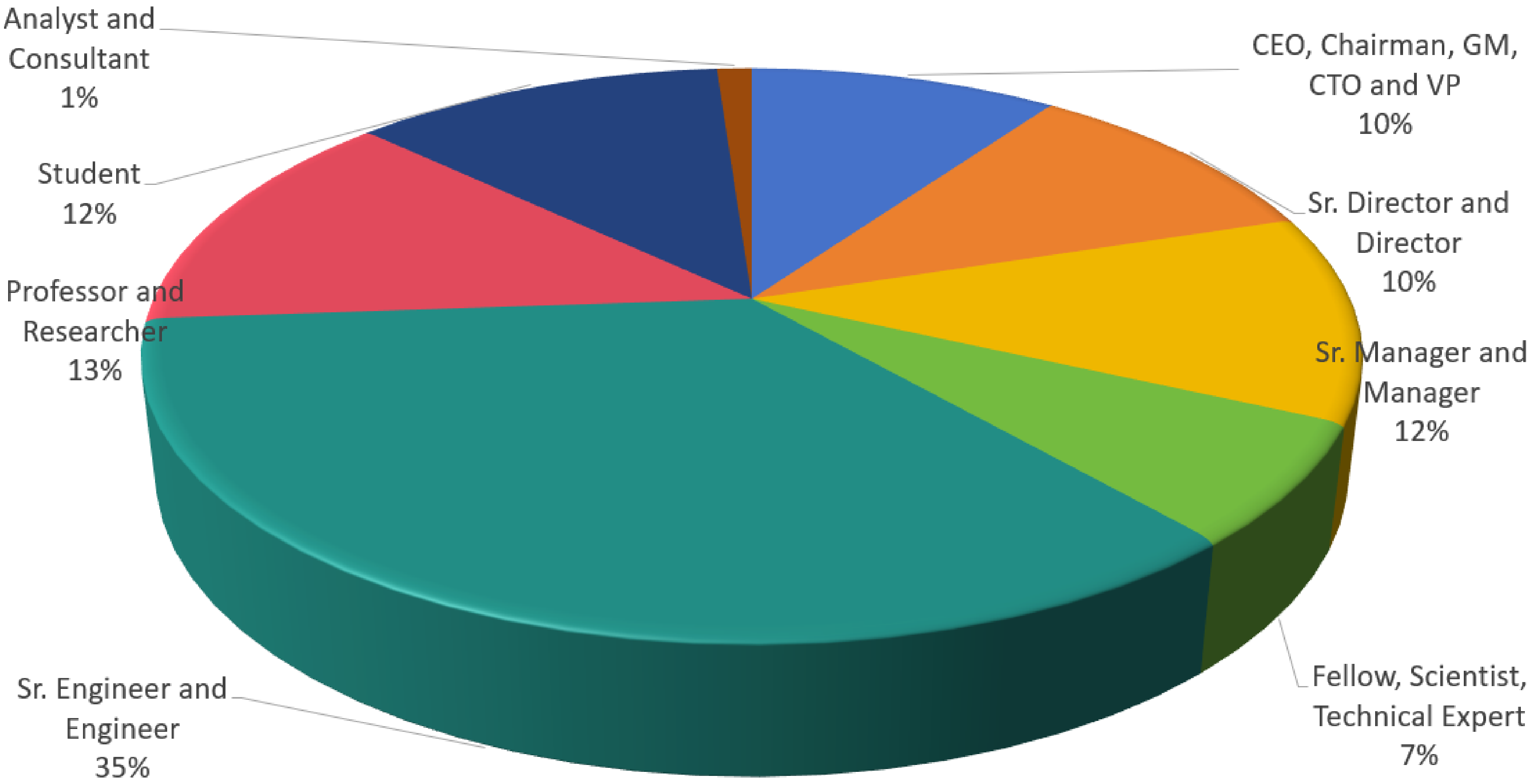
CSTIC 2026 Attendees

70% attendees from industry, while 30% from universities and institutes



CSTIC 2026 Attendees' Job Title

31% of the attendees were managers or above, who were the decision makers in companies.



Attendees from 273 Companies, Universities and Institutes

AAA China
Advanced NanoSurface Technologies (Shenzhen) Co., Ltd.
Advantest
Afilm
Agilent
AIM Solutions B.V.
Akrion
AMEC
AMIES Technology Co., Ltd
AnChu Electronic Materials (Ningbo) Co., Ltd.
Anji Microelectronics Technology
Anteland
Applied Materials
Arrayed Materials (China) Co., Ltd.
ASML
ASMPT
Aspirng Semiconductor
BASF
Beihang University
Beijing Academy of Science and Technology
Beijing E-Town Semiconductor Technology
Beijing Golden Times Media Technology Corp.,Ltd.
Beijing Integrated Circuit Center Co., Ltd.
Beijing Jiaotong University
Beijing Naura Microelectronics
Beijing Sineva Robot Technology Co., Ltd.
Beijing Superstring
Beijing University of Posts and Telecommunications
Beijing X2Chip Technologies
Beijing Xuanjie Technology Co., Ltd
BOE
Bozhon Precision Industry Technology Co.,ltd
ByteDance

Cambridge University
Carl Zeiss SMT GmbH
CASPA
CATL
CCID
China Construction Eighth Corp
China Information and Communication Technology Group
China University of Mining and Technology-Beijing
Chips Weekly
Circuit Fabology Microelectronics Equipment Co.,Ltd
Cornerstone
CXMT
D2S, Inc.
Dalian Shuangj Trading Co., Ltd
Dalian University of Technology
Dalian Xianlian Advanced Technology Co., Ltd.
Dow Dupont
Dupont
East China Normal University
East China University of Science and Technology
Eastern Institute of Technology, Ningbo
Enshuo Information Technology Co., Ltd.
Entegris
ETH Zurich
Ferrotec(An Hui)Technology Development
Fraunhofer ENAS
Fraunhofer ENAS / ErzM-Technologies UG
Fudan Universally
Fujian Jinhua Integrated Circuit Co.,Ltd
FUJIFILM
FUJIFILM Electronic Materials (Hong Kong) Co., Ltd.
Geotech Environmental Equipment Hong Kong LTD.
Global Research & Innovative Solutions Co.,Ltd.

Go to Storage Technology (Suzhou)
GrandiT Co., Ltd.
GTA semiconductor Co.， Ltd.
Guangdong University of Technology
Guangzhou CanSemi Technology
Guyu Capital
Hangzhou GHS Semiconductor
Hanyang University
Hanyang University ERICA
Hebei GEO University
Hebei University of Technology
Hefei Sineva Intelligent Machine Co., Ltd
HHGrace
HiSilicon
Hitachi High-Tech
HLMC
Hong Kong University of Science and Technology
Hongkong University
Hongkong University of Technology
HSLab
Huali Microelectronics Corporation
Huawei
Huawei Semiconductor Division
Huawei Technologies R&D Belgium
Huazhong University of Science and Technology
Hunan Red Solar Photoelectronics
Huntsman Chemical R&D Center (Shanghai) Co., Ltd.
Hygon Information Technology Co., Ltd.
IBM
ICT, CAS
Institute of Semiconductors, CAS
Instron
Intel

Attendees from 273 Companies, Universities and Institutes

JCET
Jefferies
Jiangsu Leadmicro Nano Technology Co., Ltd.
Jice (Nanjing) Technology Co., Ltd
KCTech
Kioxia
KLA
KOKUSAI ELECTRIC CORPORATION
KU Leuven
KUNTAI MAGLEV
Lam Research
Lanzhou University of Technology
Laplace (Wuxi) Semiconductor Technology Co., Ltd
Leadmicro
Leuven Instruments
Linkoping University
Longyun (Shaoxing) Semiconductor Equipment Technology
Mentor Graphics
Merck
Merck Electronic Materials
Merck Optoelectronic Materials
Microchip Operations (Malaysia) Sdn. Bhd.
Microsoft
Mito Kogyo CO., LTD
Mitsubishi Gas Chemical Company, Inc
MNT Tech
Moses Lake (Xi'an) Chemical Industry Co., Ltd
Mycronic AB
Nanjing University
Nanjing University of Information Science and Technology
Nanjing University of Posts and Telecommunications
National Institute of Metrology
National Nanotech Innovation Center
National Taiwan Central University
NeoMem Technology
NEXCHIP SEMICONDUCTOR
Nitto Denko (China) Investment Co., Ltd.
Nova
NRL CAPITAL
NXP Semiconductors
Oip
Onto Innovation
Origin Materials Technology
Oxford Instrument
Peking University
Peng Cheng Laboratory
Phlexing
Photothermal Spectroscopy Corp
PIOTECH
PIOTECH （Shanghai）
Qnity Electronics, Inc.
Qualcomm
Quantica Computing, LLC
Quanxin Intelligent Manufacturing Technology Co., Ltd
Raintree Technologies Corp
Research Institute of Microelectronics, CAS
RUIHONG(SUZHOU)ELECTRONIC CHEMICALS CO.,LTD.
Sandisk
SANECHIPS
SBI E2-Capital Securities Limited
School of IC and Micro-Nanoelectronics Innovation, Fudan Univ.
Seichitech
Semitronix
SHANGHAI ADVANCED RESEARCH INSTITUTE，CAS
Shanghai Aipum Co., Ltd.
Shanghai Bangxin Semi
Shanghai Core Innovation Center
Shanghai Fosen
Shanghai Haina Institute of Engineering
Shanghai Hedong Electronics
Shanghai Huali Microelectronics
Shanghai Institute of Microsystem and Information Technology
Shanghai Institute of Microsystem and Information Technology, CAS
Shanghai Jiao Tong University
Shanghai KST Semiconductor Co., Ltd.
Shanghai LEDA Technology Co
SHANGHAI METASH INSTRUMENTS
Shanghai Microelectronics Equipment Co., Ltd.
Shanghai Optoelectronics Science and Technology
Shanghai PFTN
Shanghai Sinyang Semiconductor Materials
Shanghai Tech University
Shanghai United Imaging Medical Technology Co., Ltd.
Shanghai University
Shanghai University of Engineering and Technology
Shanghai Yuwei Semiconductor Technology
Shanghai Aifei Electronic Technology
ShanghaiTech University
Shanhai Jiaotong University
Shengzhen Angstrom
Shengzhou Yangtze River Delta Intelligent New Energy Vehicle Innovation Center
Shenzhen Decent Investment Co., Ltd
Shenzhen Institute of Advanced Electronic Materials International Innovation Center
Shenzhen Kaier Technology
SICA
SICARRIER
SiCreat(Suzhou) Semitech

Attendees from 273 Companies, Universities and Institutes

SiEn (Qingdao) Integrated Circuits
Silex Beijing
SIMIC Capital
Sizhuo Semiconductor Technology (Beijing)
SK Hynix
SK siltron
Skhynix Dalian
SMIC
Solstice Advanced Materials
Songshan Lake Materials Laboratory
Southeast University
Southern University of Science and Technology
Southwest China Institute of Electronic Technology
Southwest University of Transportation
SRI INTELLECTUAL
SRII
State Grid Shanxi Electric Power Research Institute
STIC
Sun Yat-Sen University
Suzhou Guansheng Semiconductor
Suzhou Huatai Electronics
Suzhou Kejingda Electronics
Suzhou Polytechnic University
Suzhou Runbang Semiconductor Materia Technology
Suzhou Sitier Software Technology
Suzhou Youlun Vacuum Equipment Technology
Taikang Asset Management (Hong Kong)
Technical University of Munich - TUM
Technische Universität Wien
The Chinese University of Hong Kong
The Chinese University of Hong Kong
Tianjin Institute of Metrology and Testing Science
Tianjin University
Tohoku University
Tokyo Electron
Toray Research Center (Shanghai) Co., Ltd.
Toray Research Center, Inc.
TRUMPF
Tsinghua University
ULVAC
University of Electronic Science and Technology of China
University of Michigan-Shanghai Jiao Tong University Joint Institute
University of Science and Technology Beijing
University of Science and Technology of China
Vital Materials
Winbond Electronics
WindTech Semi
Wisdom Semiconductor Technology
Wuhan XMC
Wuxi Huaying Microelectronics Technology
Xian Jiaotong University
Xi'an Jiaotong-Liverpool University
Xi'an Jiaotongpool University in Suzhou
Xidian University
XLMEC
Yangtze Memory Technology
YMTC
Yokohama National University
Youwei
YUANTA SECURITIES KOREA
Yunnan Yuntianhua
Zeta Tech
Zhangjiang Laboratory
Zhejiang Aoshou Material Technology
Zhejiang Lab
Zhejiang Newon Electronics Technology
Zhejiang Qiant Science Research Institute Center
Zhejiang University
Zhejiang University - Semiconductor Materials Research Center
Zhenjiang Reco New Material
Zhonghuan Advanced Semiconductor Technology
Zhuhai Cornerstone
Zhuhai Hengge Microelectronic Equipment
Zhuhai Silicon Chip Technology
ZJU-Hangzhou Global Scientific and Technological Innovation Center
ZTE
Zhejiang Yunqi Science and Technology Innovation Center

CSTIC 2026 Distinguished Conference Plenary Speakers

Mr. Aki Fujimura
Chairman and CEO
D2S, Inc., USA

Prof. Arokia Nathan
Bye-Fellow and Tutor
at Darwin College
Cambridge University, UK

Dr. Zongliang Huo
Chief Scientist
Yangtze Memory Technology, China

Mr. Jiye Yang
Vice President
HHGrace, China

09:25-10:00 **Changing the Face of Silicon: Curvy Manufacturing Will Lead to Curvy Design**
Mr. Aki Fujimura
Chairman and CEO, **D2S, Inc.**, USA

10:00-10:35 **Fundamentals of Thin-Film Transistors: From Structure to Applications**
Prof. Arokia Nathan
Bye-Fellow and Tutor at Darwin College, **Cambridge University**, UK

10:35-11:10 **Xtacking Architecture Assist Future Chip Innovation and Development**
Dr. Zongliang Huo
Chief Scientist, **Yangtze Memory Technology**, China

11:10-11:45 **Delving Deep into Advanced Power Technology for a Green Future**
Mr. Jiye Yang
Vice President, **HHGrace**, China

10 Symposiums with 124 Invited Speakers

Symp I: Device Engineering and Memory Technology

Symp. II: Lithography and Patterning

Symp. III: Dry &Wet Etch and Cleaning

Symp. IV: Thin Film, Plating and Process Integration

Symp. V: CMP and Cleaning

Symp. VI: Metrology, Reliability and Testing

Symp. VII: Advanced Packaging and Heterogeneous Integration

Symposium VIII: More than Moore and Emerging Semiconductor Technologies

Symp. IX: Design and Automation of Circuits and Systems

Symp. X - AI & IC Manufacturing

CSTIC 2026

集成电路科学技术大会

Conference of Science & Technology for Integrated Circuits (CSTIC) 2025

Prof. Mario Lanza
Associate Professor
National University of Singapore

Prof. Vita Pi-Ho Hu
Professor
Taiwan University, China

Dr. Leo Pang
Vice President
D2S, Inc., USA

Dr. Hideaki Tsubaki
Manager
FUJIFILM, Japan

Prof. Han Wang
Professor
University of Hong Kong

Prof. Heng Wu
Associate Professor
Peking University

Ben Zongbin Wang
Director
Applied Materials

Prof. Jin-Goo Park
Professor
Hanyang University ERICA, Korea

Dr. Knut Gottfried
CEO & CTO / Co-Owner
ErzM-Technologies UG, Germany

Prof. David Keezer
Chair Professor
Eastern Institute of Technology, Ningbo
IEEE Life Fellow

Prof. Zebo Peng
Professor
Linköping University, Sweden

Dr. Knut Gottfried
CEO & CTO / Co-Owner
ErzM-Technologies UG, Germany

Mr. Ray Saupe
Senior Researcher & Project Manager
Fraunhofer ENAS, Germany

Prof. Ulf Schlichtmann
Professor
Technical University of Munich (TUM), Germany

Prof. Wenjian Yu
Professor
Tsinghua University, China

Dr. Tsung-Yi Ho
Professor
The Chinese University of Hong Kong

Dr. Chiayen Li
Head of AI Research and Development
Nexchip Semiconductor Corporation

Dr. Jim Zhang
Senior Manager
Lam Research

Dr. Zhonghua Jin
Senior Staff Engineer
Beijing Superstring Academy of Memory Technology

Dr. Kai Cheng
Board Chair&President
Enkris Semiconductor, Inc.

Panel Discussion 1

What will Shape the Semiconductor Landscape for the Next Decade?

Moderators:

Prof. Cor Claeys
KU Leuven, Belgium

Prof. Qianqian Huang
Peking University, China

Panelists:

Prof. Arokia Nathan
Cambridge University, UK

Dr. Peng Bai
HHGrace, China

Dr. David Wang
Renowned Executive and Innovator, USA

Dr. Changze Liu
Huawei Semiconductor Division, China

Mr. Aki Fujimura
D2S, Inc., USA

Dr. Jun Yuan
Qualcomm, USA

Panel Discussion 2

Women and Young Professionals Pioneering the Future of Electronics

SEMI U Tutorial 1: Plasma Etch and Advanced Patterning

Date:	08:45-10:15 on March 24, 2026
Venue:	3F, Kerry Hotel Pudong, Shanghai
Meeting Room:	Pudong Ballroom 5

Speaker 1: Dr. Cheng Qi, Technical Expert, Shanghai Huali Microelectronics, China

Biography:

Dr. Cheng, Qi received the Ph.D degree from University of Missouri, Columbia, U.S.A. in electrical and computer engineering. He holds several patents and has published more than 10 international journal or conference papers.

He is currently a technical expert in Shanghai Huali Microelectronics. He served as many critical roles of process R&D in semiconductor industry. His expertise includes process and equipment co-optimization of ICP, CCP and special etch, advanced patterning and advanced process integration. He also has strong experience of strategic planning and technical roadmap design for top wafer fabrication equipment (WFE) company to drive revenue growth and increase market share in new domain.

Speaker 2: Mr. Zheng Tao, Vice President of etching product center, Leuven Instruments, China

Biography:

Mr. Zheng Tao serves as the vice president of etching product center at Leuven Instruments. He leads the research projects for the development of Chimera 300mm ICP etch systems for advanced node of logic and memory devices. His research focus is on process technology and integration, advanced patterning, ion beam etch technology and plasma physics. Prior to joining Leuven Instruments, he was PMTS in advanced patterning department of imec for over 10 years. Prior to that, he worked for AMEC, Sony, UMCi, Lam research in the field of plasma etch and process development since year 2000. Mr. Zheng Tao received his bachelor degree in Chemistry from Fudan University, China. He holds more than 30 patents and has published ~10 academic papers in international journals and conferences.

SEMI U Tutorial 2: Computing-in-Memory (CIM)

Date: 10:30-12:00 on March 24, 2026
Venue: 3F, Kerry Hotel Pudong, Shanghai
Meeting Room: Pudong Ballroom 5

Speaker 1: Dr. Shaodi Wang, CEO of Witmem

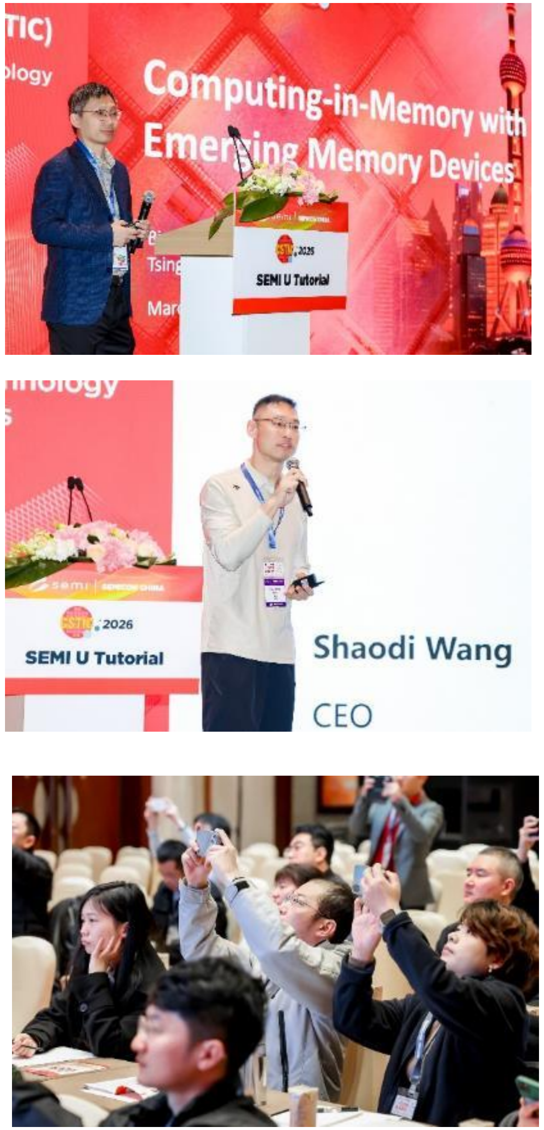
Biography:

Shaodi received his B.S. degree from Peking University in 2011.and the Ph.D. degree from UCLA in 2017. He founded Witn Co. Ltd in 2017, and currently serves as the CEO of Witmem. Shaodi and Witmem are dedicated to developing in-memory computing (IMC) technology. Since 2022, Witmem have multiple mass-production chips in markets.

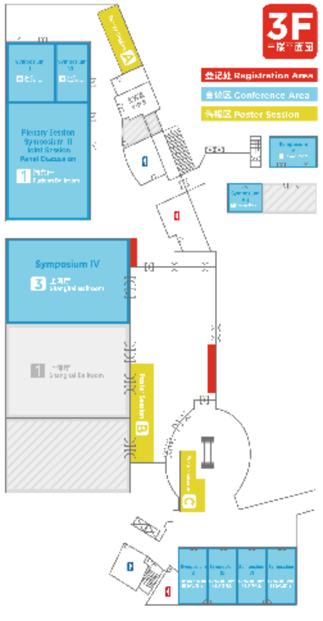
Speaker 2: Prof. Bin Gao, Full Professor, Tsinghua University

Biography:

Prof. Gao is currently a Full Professor with the School of Integrated Circuits, Tsinghua University. He received the B.S. degree in 2008 and Ph.D. degree in 2013, both from Peking University. He has been a visiting scholar in Nanyang Technical Univeristy, Singapore, and Stanford University, USA. He joint Tsinghua University in 2015, and was promoted to Associate Professor with tenure in 2022. His current research interests include advanced memory technologies and computation-in-memory chips. He has published more than 100 journal papers on Science, Nature, Nature Electronics, Nature Nanotechnology, Nature Machine Intelligence, and more than 50 papers on the top conferences (IEDM, ISSCC, VLSI). His total citation is over 18000. He served as Sub-committee Chair of IEDM (2021), IRPS (2023, 2024), EDTM (2021), and ICTA, and TPC member of DAC, IMW, IPFA, etc.



CSTIC 2026 Poster Session



This Floor Plan is for use at CSTIC 2026 on March 22-23

16:00-18:00 March 23

Poster Area A： Symp VI， VII， VIII， IX
Poster Area B： Symp II， III， IV
Poster Area C： Symp I, V, X

Onsite and online voting with lucky draw

CSTIC 2026 调查问卷 Survey

CSTIC 2026 Executive Committee Team


Prof. Bin Yu
Conference Chair
Professor, Zhejiang University, China


Dr. Peng Bai
Conference Executive Co-Chair
President, HHGrace, China


Prof. Cor Claeys
Conference Co-Chair and Award Selection Chair
Professor, KU Leuven,


Dr. Steve X. Liang
Conference Co-Chair and Symp-VII Chair


Dr. Beichao Zhang
Conference Co-Chair
VP of Hangzhou GHS Semiconductor, China


Prof. Qianqian Huang
Symp-I Chair
Professor, Peking University, China


Dr. Linyong (Leo) Pang
Symp-II Chair
Vice President, D2S Inc., USA


Dr. Kaidong Xu
Symp-III Chair
CEO, Leuven Instruments, China


Dr. Xiaoping Shi
Symp-IV Chair
General Manager, Akrion Italy


Prof. Xinping Qu
Symp-V Chair
Professor, Fudan University, China


Dr. Xiaowei Li
Symp-VI Chair
Deputy Director, ICT, CAS, China


Prof. Jianshi Tang
Symp-VIII Chair
Associate Professor, Tsinghua University, China


Prof. Pingqiang Zhou
Symp-IX Chair
Associate Professor, Shanghai Tech University, China


Prof. Cheng Zhuo
Symp-X Chair
Professor, Zhejiang University, China


Dr. Hsiang-Lan Lung
Poster Chair
Director, MXIC, Taiwan, China

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Fosen 福讯电子

Piotech 拓荆科技

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ANJI

AMEC

Organizer: semi

Co-organizer: SAMT 北京超弦存储器研究院

Co-sponsor: Electron Devices Society

CSTIC 2027 Call for Papers

Time: March 21 ~ 22(Sunday-Monday), 2027
(SEMICON China 2027， March 24-26)

CSTIC 2027 call for papers and manuscript deadlines:

Abstract Due: Sep. 30, 2026

Author Notification: Oct. 15, 2026
Manuscript Due: Dec. 15, 2026
Presentation Due: Feb. 20, 2027
Copyright Due: Feb. 10, 2027

Conference Date: Mar. 21-22, 2027

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CSTIC 2026

Thank you and see you @ CSTIC 2027